



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A977*UR15AJ6	A	MU1A	2015-08-03
Amount	UoM	Unit type	ST ECOPACK Grade	
1910.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminat	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	15.9 - 11 - 3.5	20	gull wing	
Comment	Package: PowerSO 20 .43 SLUG DOWN; MDF valid for L6205PD; L6205PD013TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A977*UR15AJ6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	14.586	mg	supplier	die	Silicon (Si)	7440-21-3		14.193	mg	973056	7431
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	6033	46
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.080	mg	5485	42
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.123	mg	8433	64
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	548	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1508	12
Leadframe	Copper & its alloys	397.459	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	4936	38
				supplier	alloy	Copper (Cu)	7440-50-8		392.060	mg	986416	205267
				supplier	alloy	Iron (Fe)	7439-89-6		0.393	mg	989	206
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.118	mg	297	62
				supplier	metallization	Silver (Ag)	7440-22-4		4.888	mg	12298	2559
Soft solder	Solder	9.231	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	9.001	mg	975084	4713
				supplier	solder	Silver (Ag)	7440-22-4		0.138	mg	14950	72
				supplier	solder	Tin (Sn)	7440-31-5		0.092	mg	9966	48
Bonding wire	Other inorganic materials	1.508	mg	supplier	wire	Copper (Cu)	7440-50-8		1.508	mg	1000000	790
encapsulation	Other inorganic materials	1485.560	mg	supplier	mold compound	silica vitreous	60676-86-0		1249.799	mg	841298	654345
				supplier	mold compound	Phenolic resin	29690-82-2		65.331	mg	43977	34205
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		51.129	mg	34417	26769
				supplier	mold compound	carbon black	1333-86-4		2.841	mg	1912	1487
				supplier	mold compound	Epoxy resin	25068-38-6		65.331	mg	43977	34205
connections coating	Solder	1.656	mg	supplier	mold compound	Biphenyl epoxy resin	85954-11-6		51.129	mg	34417	26769
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.656	mg	1000000	867